Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	5 X 5 X 0.85
Lead Count	24
Terminal Finish	100 Sn
MS Number	

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.57E-02	93.70	937000	41.67	416749
Thermosets	Epoxy Resin	Proprietary	8.22E-04	3.00	30000	1.33	13343
Thermosets	Phenol Resin	Proprietary	8.22E-04	3.00	30000	1.33	13343
Other inorganic materials	Carbon Black	1333-86-4	8.22E-05	0.30	3000	0.13	1334
Subtotal			2.74 E-02	100.00	1000000	44.48	444769

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	2.91 E-02	97.50	975000	47.18	471819
Copper & its alloys	Iron	7439-89-6	7.01 E-04	2.35	23500	1.14	11372
Copper & its alloys	Zinc	7440-66-6	3.58 E-05	0.12	1200	0.06	581
Copper & its alloys	Phosphorus	7723-14-0	8.95 E-06	0.03	300	0.01	145
Subtotal			2.98 E-02	100.00	1000000	48.39	483917

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	7.45 E-05	100.0	1000000	0.12	1210

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.41 E-03	100.0	1000000	2.28	22837

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	2.14 E-04	100.0	1000000	0.35	3480

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Gallium Arsenide	1303-00-0	2.21 E-03	100.0	1000000	3.59	35886

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	3.28 E-04	89.00	890000	0.53	5323
Thermoset	2-Butoxyethyl acetate	112-07-2	3.69 E-05	10.00	100000	0.06	598
Other organic materials	2-Propenoic acid, 3-(trimethoxysilyl)propyl ester	4369-14-6	3.69 E-06	1.00	10000	0.01	60
Subtotal			3.69 E-04	100.0	1000000	0.60	5981

Die Coat

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other organic materials	Dimethylsiloxane	68083-19-2	7.15 E-05	60.40	333337	0.12	1160
Other organic materials	Dimethylvinylated & Trimethylated silica	68988-89-6	3.31 E-05	28.00	154527	0.05	538
Other organic materials	Dimethyl, Methylhydrogen siloxane	68037-59-2	1.18 E-05	10.00	55188	0.02	192
Other organic materials	Ethylbenzene	100-41-4	1.18 E-06	1.00	5519	0.002	19
Other organic materials	Xylene	1330-20-7	7.10 E-07	0.60	3311	0.001	12
Subtotal			1.18 E-04	100.0	551883	0.19	1920

	Weight (g)	Percentage (%)	PPM
Package Totals	**6.16 E-02**	**100**	**1000000**

Note: The information provided in this declaration are true to the best of ADI's knowledge.
ADI derived most of the information listed in this declaration from documents provided by third parties, and assumes no liability to any inaccuracy of such information.

ANALOG DEVICES
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